

<p>95-317920/41 A85 L03 (A26) SUMM 94.01.28 SUMTOMO METAL MINING CO *JP 07216553-A 94.01.28 94JP-008535 (95.08.15) C23C 18/28, B32B 15/08, C25D 5/12, H05K 3/38 Prodn. of copper-coated polyimide substrate - by etching surface of polyimide resin film, surface-treating with alkali soln., applying catalyst, activating, electroless plating, heat-treating, and forming C95-141368</p>	<p>A(5-11, 11-C4B1, 11-C4D, 12-S6B) L(3-H4E1, 3- H4E3, 4-C24A) ADVANTAGE Polyimide resin film has high adhesion strength even with thick polyimide resin film. (4pp003DwgNo.0/0)(NA) (4ppDwgNo.0/0)</p>
<p>The prodn. of Cu-coated polyimide substrates comprises subjecting the surface of the polyimide resin film to etching, and then surface- treating with an alkali soln. of concn. 0.1-5 mol/l at 0-50° C; applying a catalyst for electroless plating; activating the applied catalyst; electroless-plating one of Ni, Co or other metal alloy; heat-treating the obtd. plated material in an inert atmos.; and forming electro-Cu plating on the electroless plating layer. Na hydroxide soln. or K hydroxide soln. is used as the alkali soln..</p> <p><u>USE</u> Used to produce Cu-coated polyimide substrates for printed- wiring boards (PWB), e.g., flexible printed circuit (FPC) or tape- automatic bonding (TAB) tape.</p>	<p>JP 07216553-A</p>